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Technical drawing of a mechanical part showing three views: front, side, and top.

Front View:

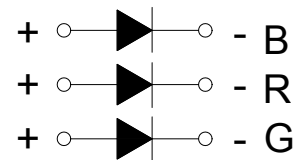
- Overall width: 5.50
- Inner width: 5.00
- Overall height: 5.00
- Central hole diameter: $\varnothing 3.74$
- Feature diameters: $\varnothing 4.40$ and $\varnothing 3.74$
- Feature thicknesses: 0.75 and 1.00
- Feature positions: +

Side View:

- Overall height: 5.00
- Width: 1.50
- Feature: Polari Mark

Top View:

- Overall width: 4.40
- Overall height: 1.50
- Central slot width: 1.50
- Base width: 2.80
- Base height: 0.80



Drawing bibliography



3 Characteristic

Forward c rren	If	30	mA			
Re er e ol age	Vr	5	V			
Po er di ipa ion	Pd	110	mW			
Opera ing empera re range	Top	-25 +80	C			
S orage empera re range	T g	-30 +80	C			
Peak p l ing c rren 1/8 d f=1KH	Ifp	125	mA			
Wa eleng h a peak emi ion (R)	If=20mA	peak	620	625	630	nm
Wa eleng h a peak emi ion (G)			515	520	525	
Wa eleng h a peak emi ion (B)			460	465	470	
Spec ral half band id h	If=20mA			10		
For ard ol age (R)	If=20mA	Vf	1.8	2.0	2.4	V
For ard ol age (G)			3.0	3.3	3.6	
For ard ol age (B)			3.0	3.3	3.6	
L mino in en i (R)	If=20mA	I	800	1000	1200	mcd
L mino in en i (G)			3000	3500	4000	
L mino in en i (B)			400	500	600	
Vie ing angle a 50% IV	If=10mA		--	120	--	Deg
Re er e c rren	Vr=5V	Ir	--	--	5	A



U ef I life	-	IF=20mA	100000			H
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Typical Electrical/Optical Characteristic Curve
(Ta=25 Unless Otherwise Noted)

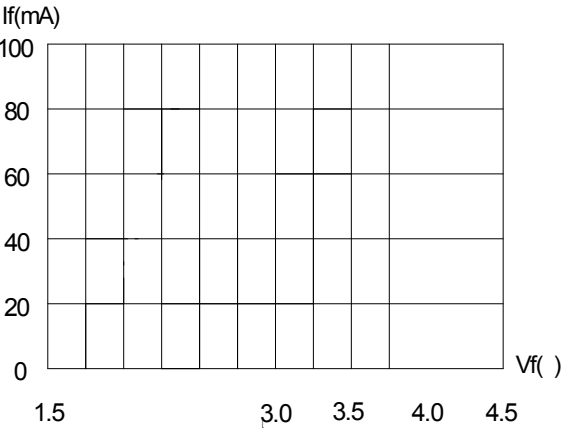


Fig.1 Forward Current vs Forward Voltage

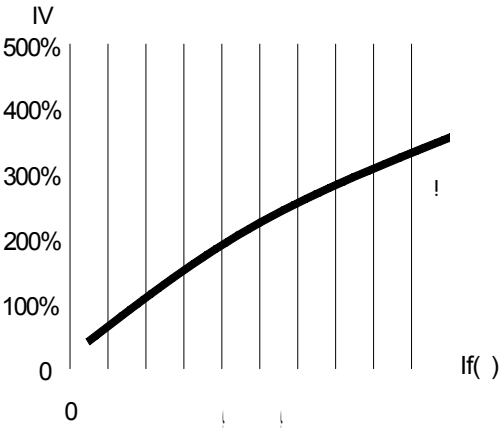


Fig.2 Relative Luminous Intensity vs Forward Current

L

W

195

i Iron Soldering: The Iron (max 30W) end temperature should be less than 300°C, soldering time 3 seconds, soldering position is minimum 2mm from board.

ii Dip Soldering: Max temperature 260°C, time 5s, solder position is minimum 2mm from board.

i Bracket must be bent only 15° from vertical.

ii Bracket mould must be finished before or after soldering.

iii Bracket mould must be finished before soldering.

i Bracket mould should be the same as the component, the distance gap of lead and hole in board.

i. It should be paid attention to the ordering of all the devices in case of wrong polarity. The device can be inserted into the component, working condition can replace the limit.

ii. It should not assemble LED when the lead is deformed.

iii. When deciding on a component in hole, accurately according to the length of hole and hole distance.

i. Soldering should be done in the correct direction.

i. d h m

